

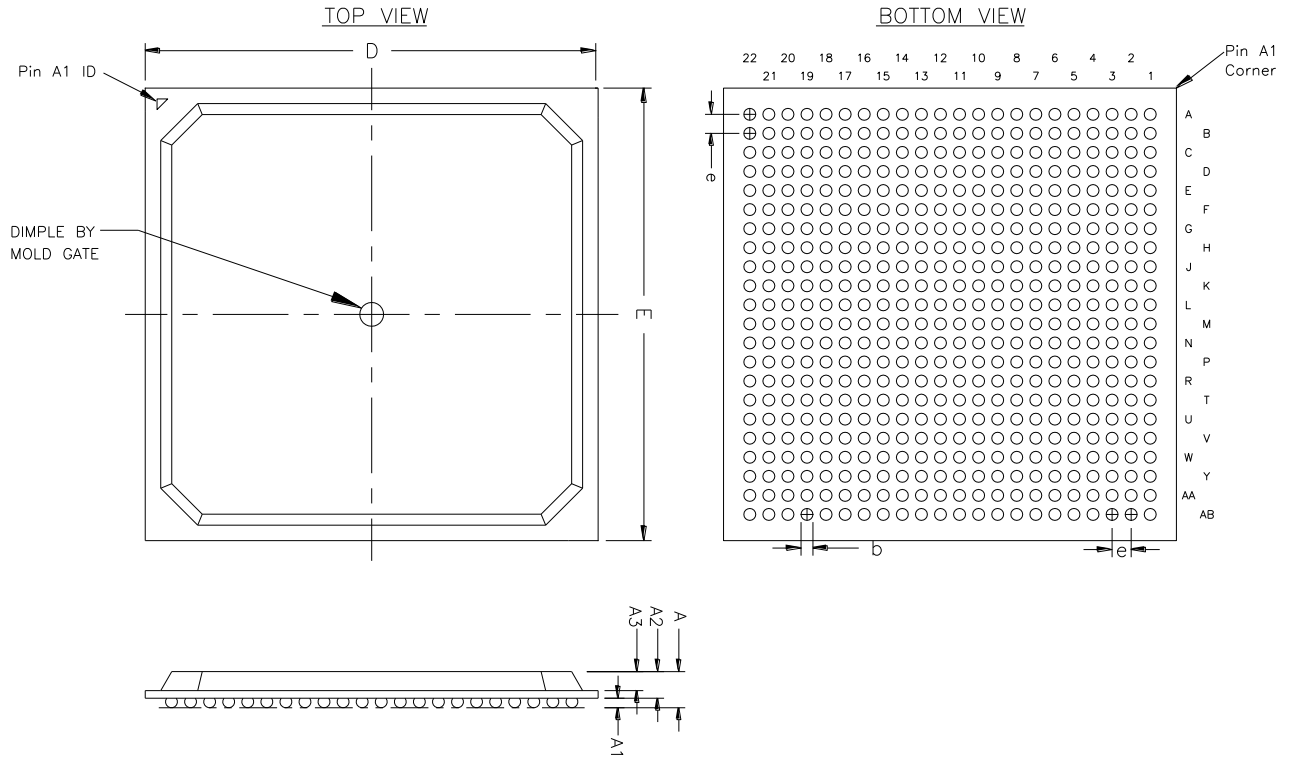
484-Pin Ultra FineLine Ball-Grid Array (UBGA) - Wire Bond - A:1.90

- All dimensions and tolerances conform to ASME Y14.5M – 1994.
- Controlling dimension is in millimeters.
- Pin A1 may be indicated by an ID dot, or a special feature, in its proximity on package surface.

Package Information	
Description	Specification
Ordering Code Reference	U
Package Acronym	UBGA
Substrate Material	BT
Solder ball composition	Regular: 63Sn:37Pb (Typ.) Pb-free: Sn:3Ag:0.5Cu (Typ.)
JEDEC Outline Reference	MO-308 Variation: AAG-2
Lead Coplanarity	0.005 inch (0.12 mm)
Weight	1.4 g (Typ.)
Moisture Sensitivity Level	Printed on moisture barrier bag

Package Outline Dimension Table			
Symbol	Millimeters		
	Min.	Nom.	Max.
A	1.60	1.75	1.90
A1	0.35	0.40	0.45
A2	1.15	1.35	1.55
A3	0.75	0.80	0.85
D	19.00 BSC		
E	19.00 BSC		
b	0.45	0.50	0.55
e	0.80 BSC		

Package Outline



Document Revision History

Table 1 shows the revision history for this document.

Table 1. Document Revision History

Date	Version	Changes
December 2011	1.0	Initial release
August 2014	2.0	Change the JEDEC Outline Reference from “MO-275 Variation: PPAA-2” to “MO-308 Variation: AAG-2”



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